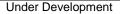


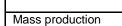
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| Under Development |  |
|-------------------|--|
| Mass production   |  |

| Clien     | t Name       |          |       |              |
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| Clie      | ent P/N      |          |       | _            |
| Pro       | duct P/N     |          |       | _            |
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| Approval  | Audit        | Approval | Audit | Confirmation |
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| Qualified | Disqualified | DATE:    |       | 1            |

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HONGLITRONIC 鸿利光电

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<u>LM</u> 003



OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Dimension 19.0mm×19.0mm×1.6mm

19.0mm×19.0mm×1.6mm

● CRI: Ra 80 80

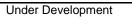
Wide viewing angle : 120°120°

RoHS compliant ROHS

sulphation corrosion resistance

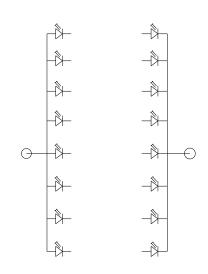
Manual Soldering

- Down light
- Spot light





Mass production



Tolerance unless otherwise specified:  $\pm 0.3$ mm.  $\pm 0.3$ 

| Input power range           | Pi               | 16                     | 26  | 46   | W  |
|-----------------------------|------------------|------------------------|-----|------|----|
| operating current range     | IF               | 480                    | 700 | 1200 | mA |
|                             |                  |                        |     |      |    |
| Junction Temperature        | Tj               | 120 °C                 |     |      | C  |
| Operating Temperature Range | Тор              | -35 °C To +85 °C       |     |      |    |
| Storage Temperature Range   | Tstg             | -40 ℃ To +85 ℃         |     |      |    |
| Lead Soldering Temperature* | T <sub>SOL</sub> | Max. 350 for 5sec Max. |     |      |    |

Notes for Table:

1.The temperature of Aluminum PCB do not exceed 85 If the input power reach 80% max Pi, the temperature of Aluminum PCB should be control below 75

85 80% 75

2. When hand soldering, keep the temperature of iron below less 350 less than 5seconds

350 ,

.3.D.C. Current : Tj = Ts + Rj-s  $\times$  Pi



| Under Development |  |
|-------------------|--|
| Mass production   |  |

|  |   | IF=700mA     | 34   | 36   | 40   | _   | V  |
|--|---|--------------|------|------|------|-----|----|
|  |   | TC=2700K     | 2860 | 3010 | 3260 | 120 |    |
|  |   | TC=3000K     | 3050 | 3150 | 3320 | 124 |    |
|  | Φ | TC=3500K     | 3050 | 3150 | 3320 | 124 |    |
|  |   | TC=4000K     | 3190 | 3350 | 3600 | 134 |    |
|  |   | TC=5000K     | 3160 | 3300 | 3550 | 132 | Lm |
|  |   | TC=5700K     | 3160 | 3300 | 3550 | 132 |    |
|  |   | TC=6000±300K | 3160 | 3300 | 3550 | 132 |    |
|  |   | TC=6500K     | 3160 | 3300 | 3550 | 132 |    |
|  |   | IF=700mA     | 80   | _    | _    |     |    |
|  |   | IF=700mA     | _    | 0.87 | _    | _   | /W |

2700K 3000K

4000K

5000K

5700K

| _ |  |  | <br> |  |
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Notes for Table

\*1.Color bins are defined at IF=700mA operation. If use different forward current, it will cause the change of chromaticity and forward voltage.

## 700mA

\*2.The tolerance of measurement at our tester is VF+/-3%, v+/-10% and Ra+/-2.

±3%, ±10% ±2

3. Tolerence of  $\pm 0.005$  on x,y coordinates.

±0.005

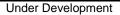
4.Color region stay within MacAdam "3-step" ellipse from the chromaticity center. but does not contain the color temperature 6000±300K. The chromaticity center refers to ANSI C78.377-2008.

3 6000±300K bin ANSI C78.377-2008



Under Development

Mass production



Mass production







## Label on box

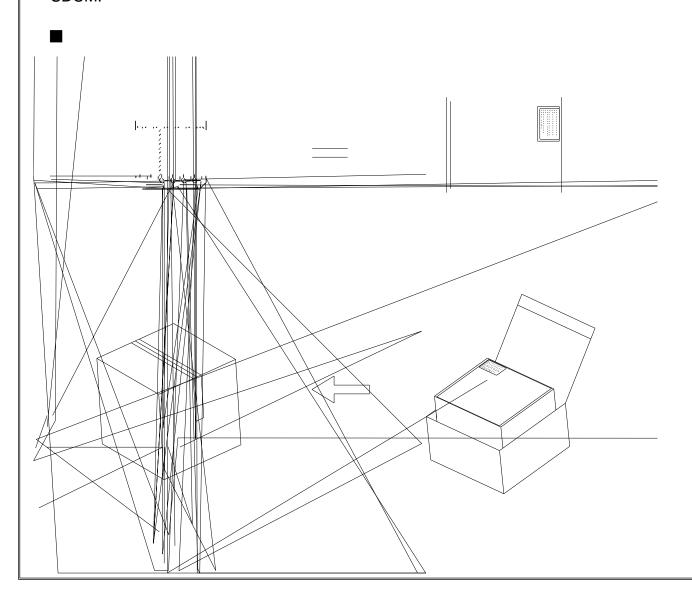
## Label on ESD shielding

V: Luminous Flux rank

VF: Forward voltage rank

TC: Color temperature

SDCM:





| Under Development |  |
|-------------------|--|
| Mass production   |  |

1. Storage

30° C

120° C±5° C

2.

350° C



Under Development

Mass production

, COB recommendation colloid surface temperature control  ${\leq}180$   $$85\,^{\circ}\!\mathrm{C}$$ 

180℃

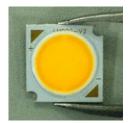
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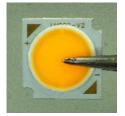
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COB 2000PPM







| Under Development |  |
|-------------------|--|
| Mass production   |  |

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